



| <b>ENVIRONMENTAL AND PACKAGE TESTING DATA FOR POWERPAK<sup>®</sup> SC-75</b> |                    |                       |                  |                    |                        |
|--|--------------------|-----------------------|------------------|--------------------|------------------------|
| <b>Stress</b>  | <b>Sample Size</b> | <b>Device Hr./Cyc</b> | <b>Condition</b> | <b>Total Fails</b> | <b>Fail Percentage</b> |
| BOND INT   | 120                | 60,000                | 200 °C + N2      | 0                  | 0.00                   |
| HAST   | 165                | 13,750                | 130 °C, 85 % RH  | 0                  | 0.00                   |
| Pressure Pot   | 110                | 10,560                | 121°, 15 PSIG    | 0                  | 0.00                   |
| Solderability  | 15                 | 360                   | 883 M2003        | 0                  | 0.00                   |
| Temp Cycle   | 165                | 82,500                | - 65 °C - 150 °C | 0                  | 0.00                   |